

SOT509-2

plastic thermal enhanced low profile ball grid array package;
304 balls; body 31 x 31 x 0.9 mm; heatsink

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HLBGA304
Package type industry code	HLBGA304
Package style descriptive code	HLBGA (thermal enhanced low profile ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-149
Mounting method type	S (surface mount)
Issue date	1-9-2005

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		30.8	-	31	31.2	mm
E	package width		30.8	-	31	31.2	mm
A	seated height		[tbd]	-	1.7	1.7	mm
A ₂	package height		0.8	-	0.9	1	mm
n ₂	actual quantity of termination		-	-	304	-	



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2. Package outline

HLBGA304: plastic thermal enhanced low profile ball grid array package; 304 balls;
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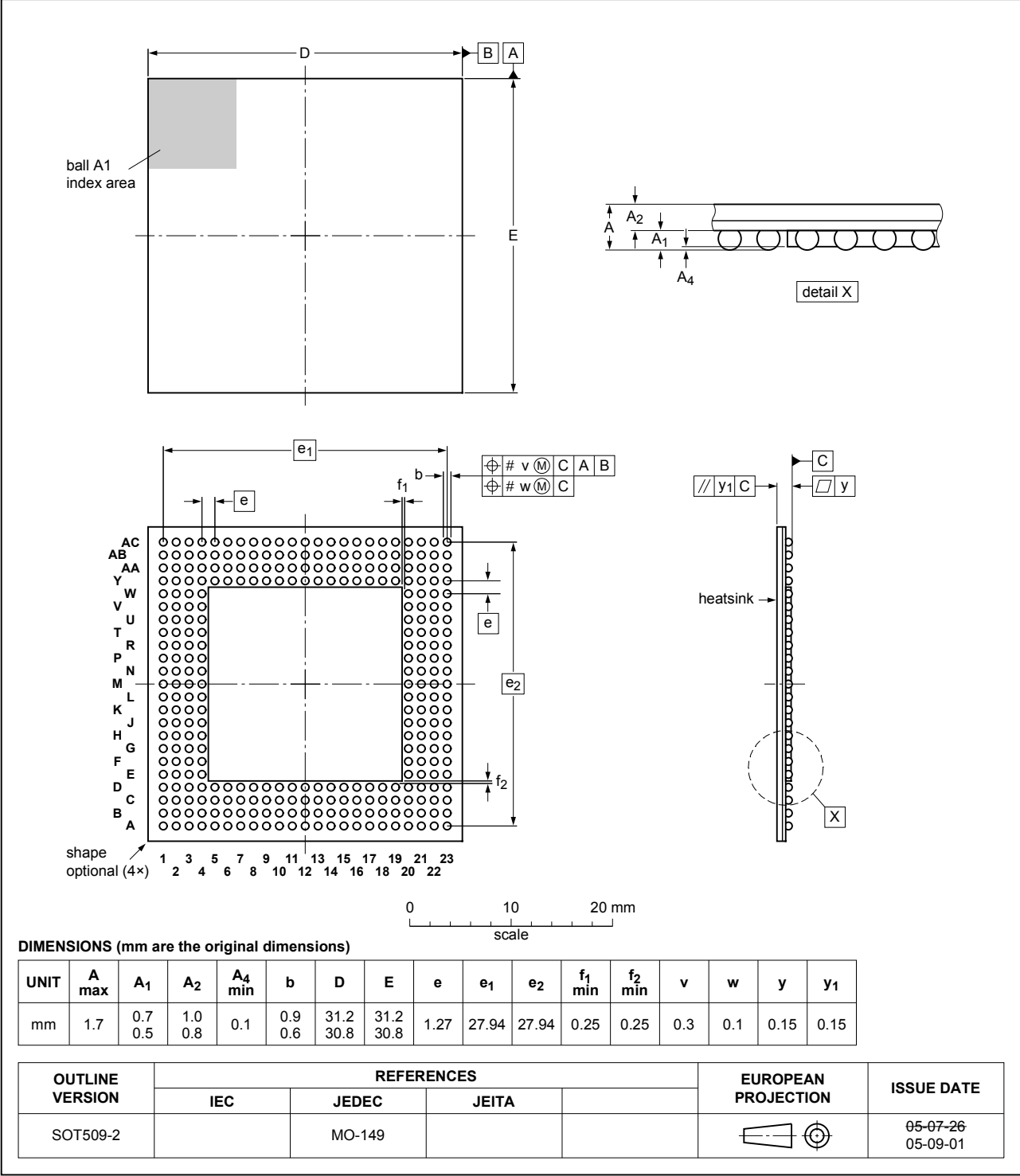


Fig. 1. Package outline HLBGA304 (SOT509-2)

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3. Legal information

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